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	Filing Date		2001-08-13	
	First Named Inventor	QUAN, SON KY		
	Art Unit	2831		
	Examiner Name	NGO, HUNG V.		
	Attorney Docket Number	SC09785T-CD1		

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1	NGUYEN, L.T., et al., "Leadframe Designs for Minimum Molding-Induced Warpage," Electronic Components and Technology Conference, 1994, Proceedings., 44th, pgs. 513-520	<input type="checkbox"/>
2	JEDEC MO-151, S-PXGA-XIPBGA Plastic Ball Grid Array Family Registration, November 1993	<input type="checkbox"/>
3	ITC, Redacted Order No. 34 - ID Granting Respondent MSD of Non-Infringement of the '306 CBI, January 6, 2011	<input type="checkbox"/>
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